

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/19/11313	
1.3 Title of PCI	New assembly process sequence in SOIC 18 lead for devices assembled in CIRTEK including single DTFS tool (Deflash, Trim, Form and Singulation)	
1.4 Product Category	See product list	
1.5 Issue date	2019-02-03	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Lorenzo NASO
2.1.2 Marketing Manager	Marcello SAN BIAGIO
2.1.3 Quality Manager	Sergio Tommaso SPAMPINATO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	CIRTEK Electronics Corp., Philippines

4. Description of change

	Old	New
4.1 Description	SOIC 18L process with separated process step/tools for Defflash/Trim and Form/Singulation	1) SOIC 18L assembly process with separated process step/tools for Defflash/Trim and Form/Singulation 2) SOIC 18L assembly process with Deflash/Trim/ Form/ Singulation -progressive process tool
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Progressing on the activities related to our service continuous improvement, ST is glad to announce the introduction of a new assembly process sequence for ST SOIC 18 leads devices assembled in CIRTEK, Philippines as additional option to increase the volume loading in assembly line.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	No change in marking, traceability guaranteed by new dedicated genealogy (Raw Line and Finished Good codes)
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7. Timing / schedule

7.1 Date of qualification results	2019-01-17
7.2 Intended start of delivery	2019-03-01
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	11313 Cirtek SOIC18L new flow with DTFS tool_report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-02-03
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9. Attachments (additional documentations)
11313 Public product.pdf 11313 Cirtek SOIC18L new flow with DTFS tool_report.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M41T83RMY6F	
	M41T83SMY6F	
	M41T83ZMY6F	
	M41T93RMY6F	
	M41T93SMY6F	
	M41T93ZMY6F	
M41T81SMY6F	M41T81SMY6F	

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Public Products List

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PCI Title : New assembly process sequence in SOIC 18 lead for devices assembled in CIRTEK including single DTFS tool (Deflash, Trim, Form and Singulation)

PCI Reference : AMS/19/11313

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M41T83ZMY6F	M41T93SMY6F	M41T93RMY6F
M41T83RMY6F	M41T83SMY6F	M41T93ZMY6F
M41T81SMY6F		



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